PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DONG WON SON	09/24/2020
JONG HO SHIN	09/25/2020
SUNG JAE LIM	09/25/2020
SUNG HO CHOI	09/25/2020
BYEONGHOON KIM	09/25/2020
CHANGOH KIM	10/08/2020
SUNGWON CHO	10/06/2020
KYOUNGHEE PARK	10/07/2020

RECEIVING PARTY DATA

Name:	STATS CHIPPAC PTE. LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17068482

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone:	480-499-9400
Email:	main@plgaz.com
Correspondent Name:	PATENT LAW GROUP: ATKINS AND ASSOCIATES
Address Line 1:	123 W. CHANDLER HEIGHTS ROAD, #12535
Address Line 4:	CHANDLER, ARIZONA 85248

ATTORNEY DOCKET NUMBER:	2515.0524 CIP
NAME OF SUBMITTER:	LISA ROSSETTI
SIGNATURE:	/Lisa Rossetti/

DATE SIGNED:	10/12/2020

Total Attachments: 8

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, DONG WON SON of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

24 Sep 2020

Date Signed

Signature for DONG WON SON

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JONG HO SHIN of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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9, 25, 2020

Date Signed

Signature for JONG HO SHIN

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNG JAE LIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 9. 25
Date Signed

Signature for SUNG JAE LIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNG HO CHOI of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 9. 25

Date Signed

Signature for SUNG HO CHOI

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYEONGHOON KIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 09. 25

Date Signed

Signature for BYEONGHOON KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, CHANGOH KIM of Incheon, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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20. 10. 08
Date Signed

Signature for CHANGOH KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNGWON CHO of Seoul, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 10. 6

Date Signed

Signature for SUNGWON CHO

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYOUNGHEE PARK of Seoul, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 10. 07
Date Signed

Signature for KYOUNGHEE PARK